

Technical Data Sheet

MODEL NO: 197UR/ANG/ANB4-INH

1.6*1.5*0.6mm Chip LED SMD

Features:

•Package in 8mm tape on 7" diameter reel

•Compatible with automatic placement equipment

•Compatible with reflow solder process

Applications:

Indicators

•Automotive : backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP	Red	
InGaN	Green	Water transparent
InGaN	Blue	

Electrical/Optical Characteristics(Ta=25°C)

Parameter	Test		Value			Unit	
	Condition	Symbol Condition		Min	Тур	Мах	- Unit
Spectral half bandwidth	IF=20mA	Δλ	R		19		nm
			G		32		
			В		27		
Dominant wavelength	IF=20mA	λD	R	620		630	nm
			G	520	525	530	
			В	460		470	
Forward voltage	IF=20mA	Vf	R	1.8		2.4	V
			G	2.8		3.7	
			В	2.8		3.7	
Luminous intensity	IF=20mA	lv	R	125	180		mcd
			G	320	500		
			В	100	130		
Viewing angle at 50% Iv	IF=10mA	2 <i>0</i> 1/2			140		Deg
Reverse current	Vr=5V	lr			10		μΑ

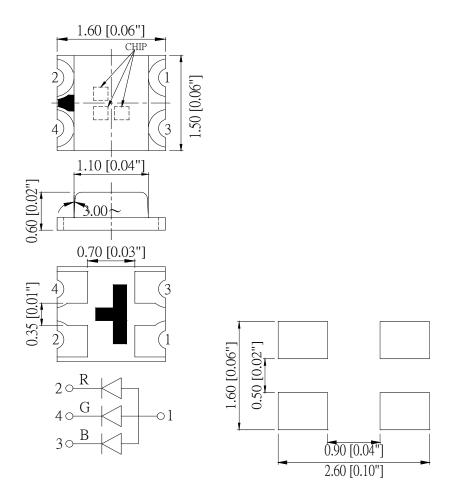
2017APR25Y



Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Value			Unit
		R	G	В	
Power dissipation	Pd	75	111	111	mW
Forward current	lf	30			mA
Reverse voltage	Vr	5			V
Operating temperature range	Тор	-40 ~+80			°C
Storage temperature range	Tstg	-40 ~+85		°C	
Peak pulsing current (1/8 duty f=1kHz)	FP	125		mA	

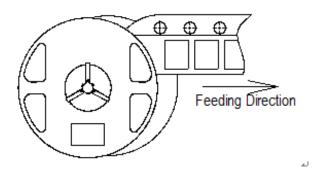
PACKAGING DIMENSIONS (mm):

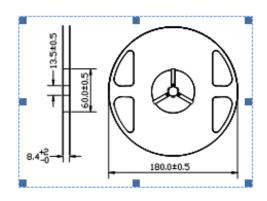




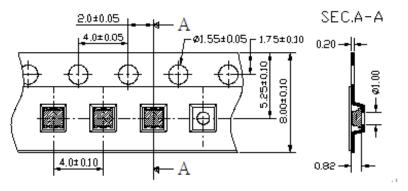
● Feeding Direction

● Dimensions of Reel (Unit: mm)~

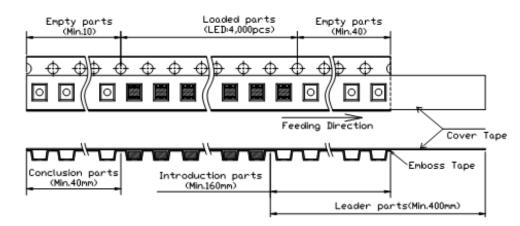




● Dimensions of Tape (Unit: mm)~



● Arrangement of Tape



■ NOTES+J

- 1. Empty component pockets are sealed with top cover tape;+/
- 2. The maximum number of missing lamps is two;+
- 3. 4,000pcs/Reel+/



Precautions For Use :

Over - current - proof

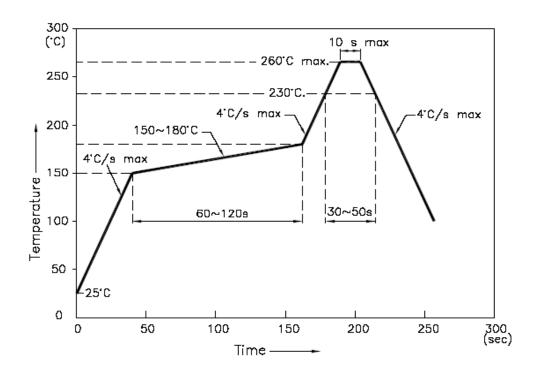
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

1. The operation of temperature and R.H. are $: 5^{\circ}$ C $\sim 30^{\circ}$ C, 60° R.H. Max.

- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}C\pm5^{\circ}C$ for 15 hrs.

■ Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245^{\circ}C(\pm 5^{\circ}C)$.the maximum soldering temperature should be limited to $260^{\circ}C$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

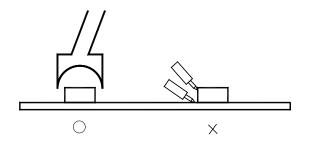


■Soldering iron

Basic spec is ≤ 5 sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec).Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 230°C .

Rework

- 1. Customer must finish rework within 5 sec under 260° C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.